

## Product Summary

V <sub>(BR)DSS</sub>	R <sub>D(on)MAX</sub>	I <sub>D</sub>
60V	2.5Ω@10V	0.3A
	3Ω@4.5V	

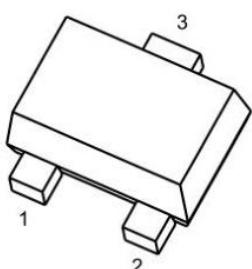
## Feature

- Trench Power MV MOSFET technology
- Voltage controlled small signal switch
- Low input Capacitance
- Fast Switching Speed
- Low Input / Output Leakage
- ESD protected
- Suffix “-Q1” for AEC-Q101

## Application

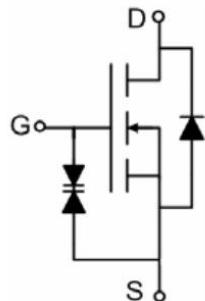
- Battery operated systems
- Solid-state relays
- Direct logic-level interface: TTL/CMOS

## Package

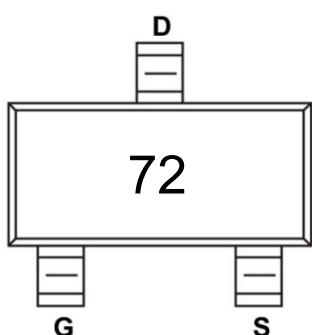


SOT-723

## Circuit diagram



## Marking



### Absolute maximum ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	60	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	0.3	A
Continuous Drain Current ( $T_A=100^\circ\text{C}$ )	$I_D(100^\circ\text{C})$	0.2	A
Pulsed Drain Current <sup>1)</sup>	$I_{DM}$	0.9	A
Power Dissipation <sup>2)</sup>	$P_D$	0.34	W
Thermal Resistance from Junction to Ambient <sup>3)</sup>	$R_{\theta JA}$	360	$^\circ\text{C}/\text{W}$
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55 ~ +150	$^\circ\text{C}$

### Electrical characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	60			V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS}=60\text{V}, V_{GS}=0\text{V}$			1	$\mu\text{A}$
Gate-body leakage current	$I_{GSS}$	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$			$\pm 10$	$\mu\text{A}$
Gate threshold voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1	1.5	2.5	V
Drain-source on-resistance	$R_{DS(\text{on})}$	$V_{GS}=10\text{V}, I_D=0.3\text{A}$		1.8	2.5	$\Omega$
		$V_{GS}=4.5\text{V}, I_D=0.2\text{A}$		2	3	
<b>Dynamic characteristics<sup>4)</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS}=30\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$		13		pF
Output Capacitance	$C_{oss}$			5		
Reverse Transfer Capacitance	$C_{rss}$			1		
Total Gate Charge	$Q_g$	$V_{DS}=30\text{V}, V_{GS}=10\text{V}, I_D=0.3\text{A}$		1.22		nC
Gate-Source Charge	$Q_{gs}$			0.5		
Gate-Drain Charge	$Q_{gd}$			0.18		
Turn-on delay time	$t_{d(\text{on})}$	$V_{DD}=30\text{V}, V_{GS}=10\text{V}, I_D=0.3\text{A}$ $R_{\text{GEN}}=50\Omega$		7		nS
Turn-on rise time	$t_r$			19		
Turn-off delay time	$t_{d(\text{off})}$			20		
Turn-off fall time	$t_f$			84		
<b>Source-Drain Diode characteristics</b>						
Diode Forward Current	$I_S$				0.3	A
Diode Forward voltage	$V_{SD}$	$V_{GS}=0\text{V}, I_S=0.3\text{A}$			1.2	V
Reverse Recovery Time	$t_{rr}$	$I_F=0.3\text{A}, di/dt=100\text{A}/\mu\text{s}$		16		nS
Reverse Recovery Charge	$Q_{rr}$			3.6		nC

Notes:

- 1) Repetitive rating; pulse width limited by max. junction temperature.
- 2)  $P_d$  is based on max. junction temperature, using junction-case thermal resistance.
- 3) The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in the still air environment with  $T_A=25^\circ\text{C}$ . The maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
- 4) Guaranteed by design, not subject to production testing.

### Typical Characteristics

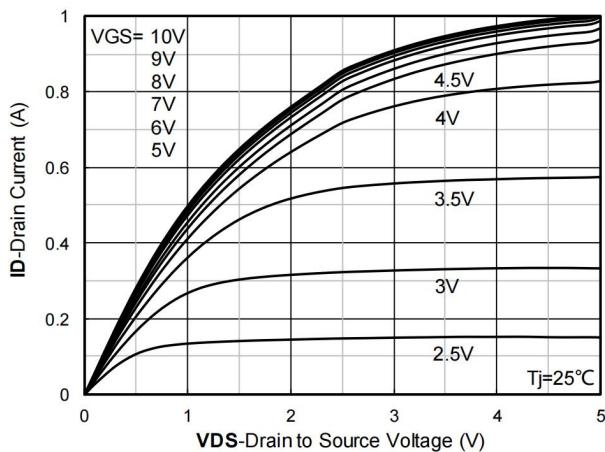


Figure 1. Output Characteristics

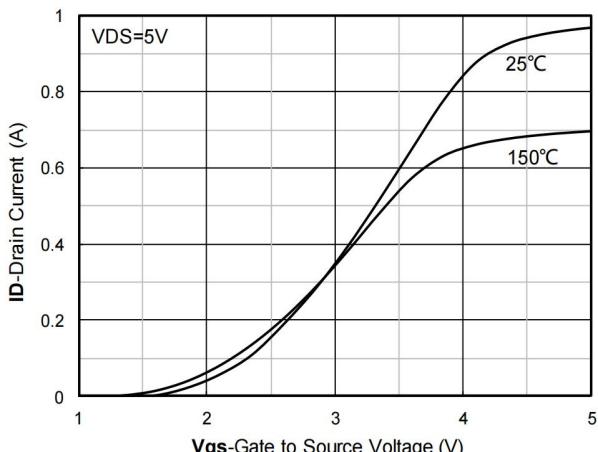


Figure 2. Transfer Characteristics

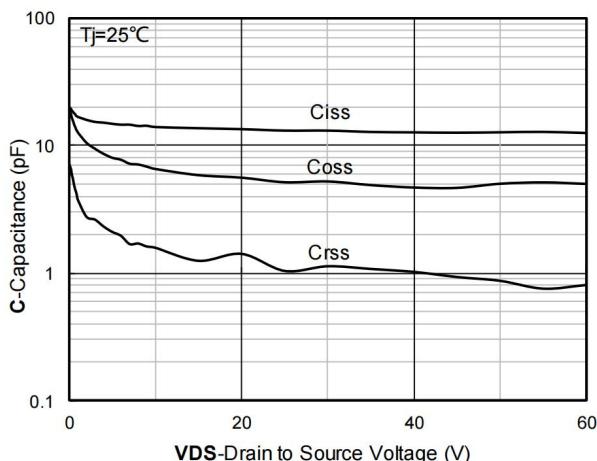


Figure 3. Capacitance Characteristics

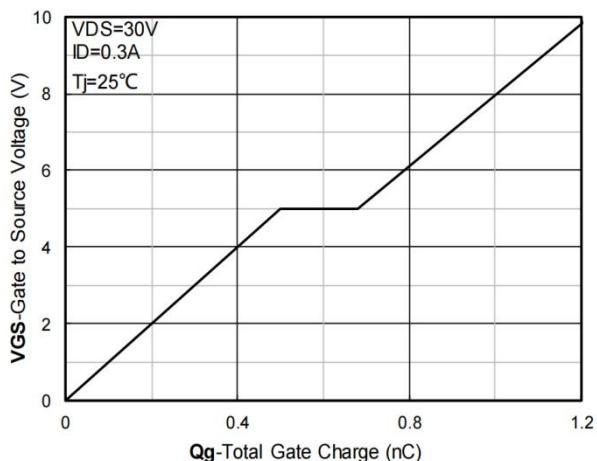


Figure 4. Gate Charge

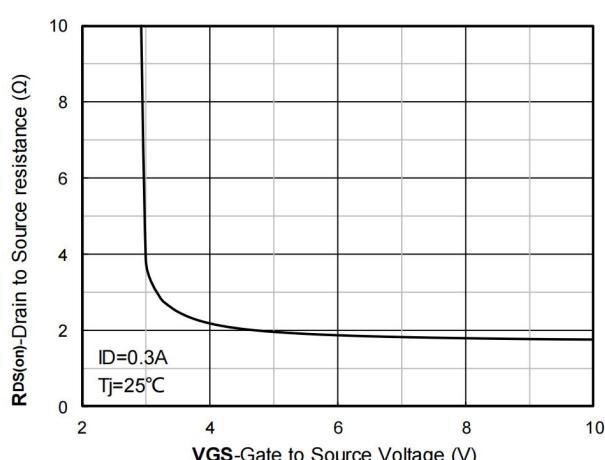


Figure 5. On-Resistance vs Gate to Source Voltage

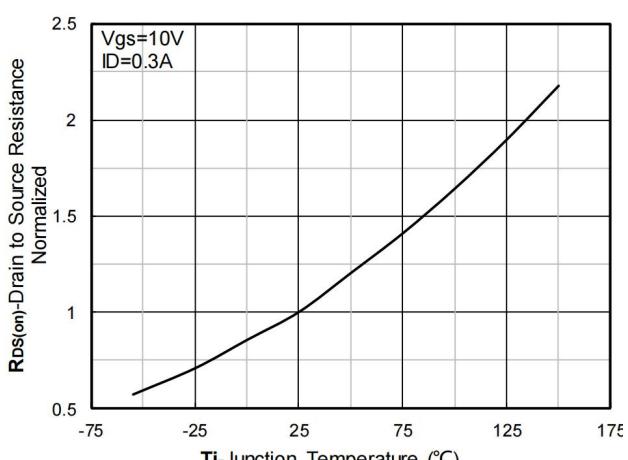


Figure 6. Normalized On-Resistance

### Typical Characteristics

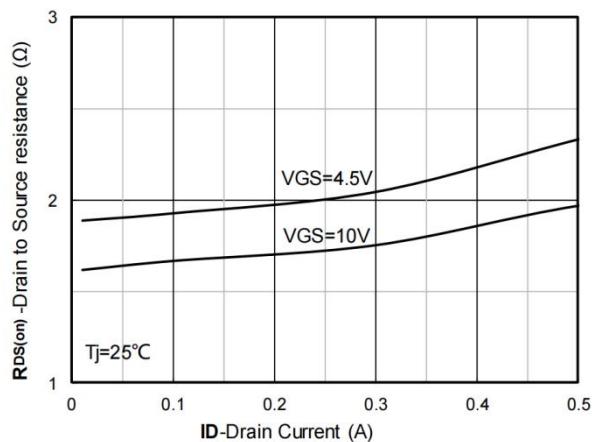


Figure 7. RDS(on) VS Drain Current

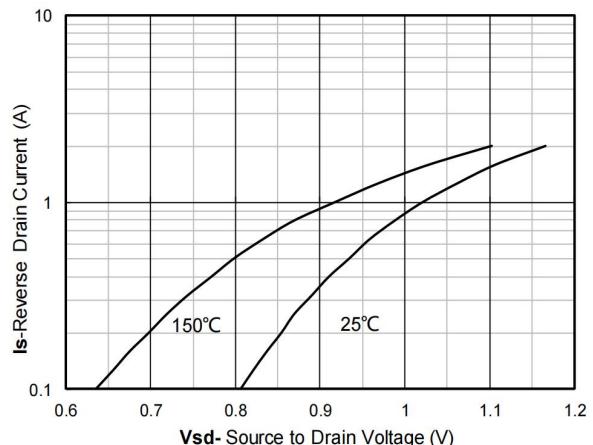


Figure 8. Forward characteristics of reverse diode

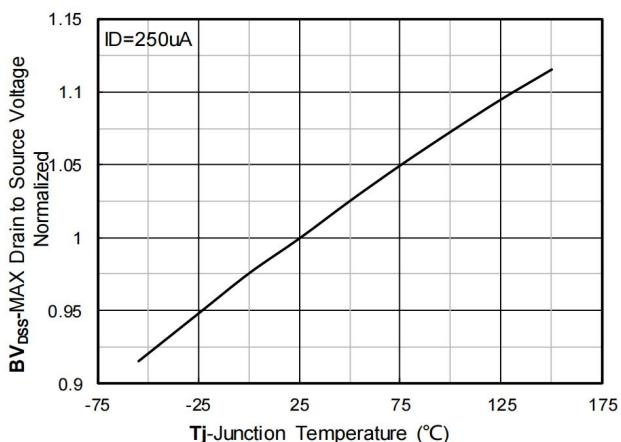


Figure 9. Normalized breakdown voltage

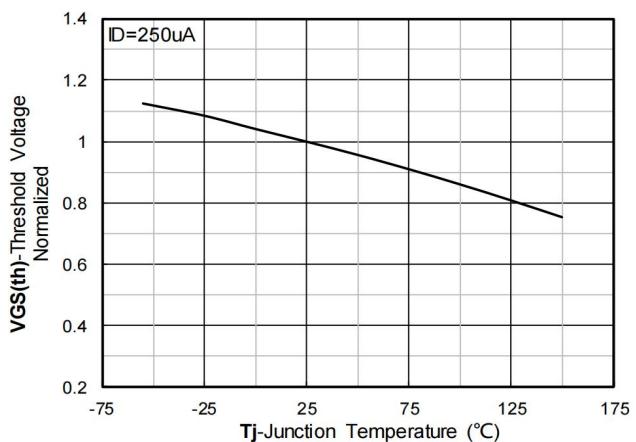


Figure 10. Normalized Threshold voltage

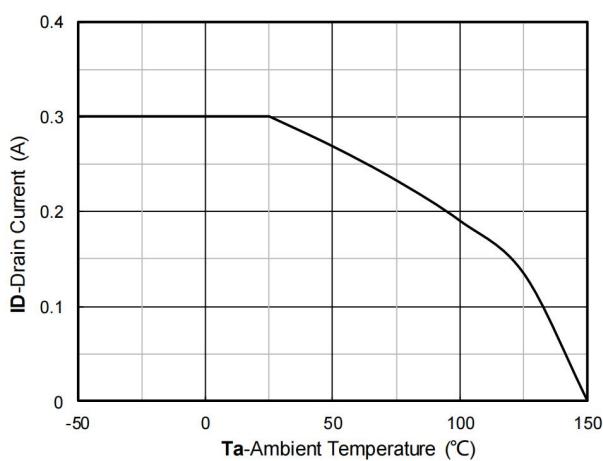


Figure 11. Current dissipation

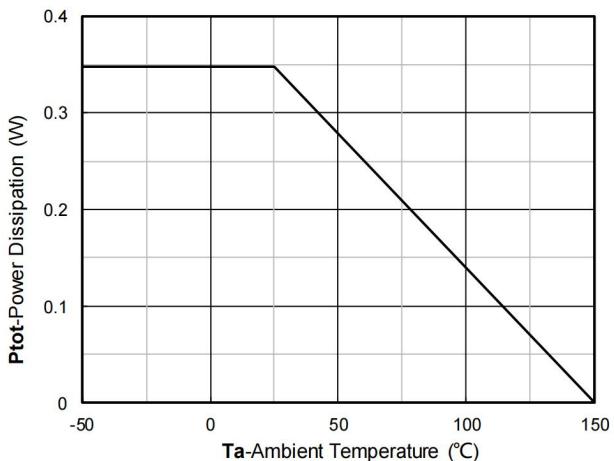


Figure 12. Power dissipation

### Typical Characteristics

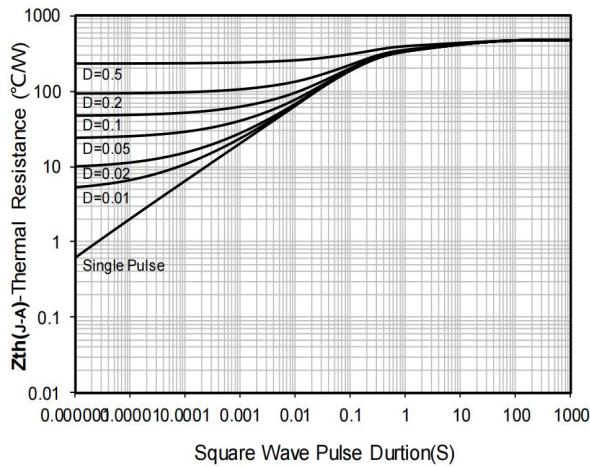


Figure 13. Maximum Transient Thermal Impedance

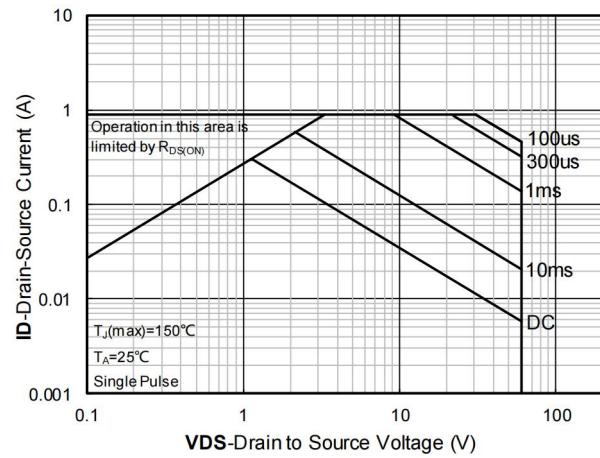
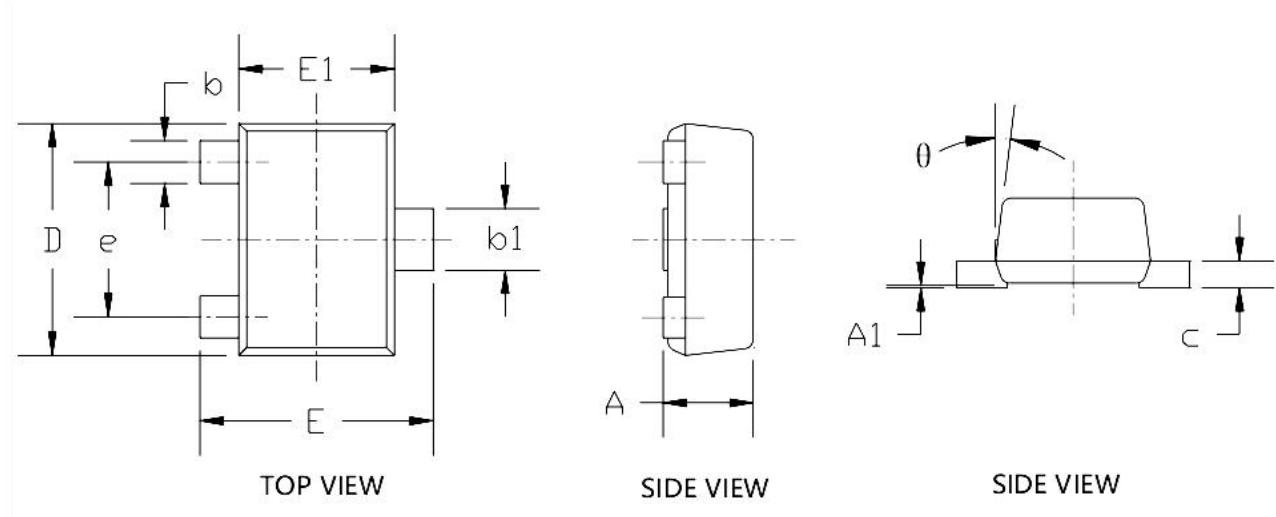


Figure 14. Safe Operation Area

## SOT-723 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.430	0.550	0.017	0.022
A1	0.000	0.050	0.000	0.002
b	0.170	0.270	0.007	0.011
b1	0.270	0.370	0.011	0.015
c	0.080	0.200	0.003	0.008
D	1.150	1.250	0.045	0.049
E	1.150	1.250	0.045	0.049
E1	0.750	0.850	0.030	0.033
e	0.800 TYP.		0.031 TYP.	
θ	7° REF.		7° REF.	